PCN Number:		20160419001					PCN Date:		5/24/2016	
Title	e: Datasheet for	r LM3263							· · ·	
<b>Customer Contact:</b>		PCN Manager					Dept:		Quality Services	
Cha	nge Type:									
	Assembly Site		☐ Design ☐ Wafe			Wafer	r Bump Site			
	Assembly Process		$\boxtimes$	Data Sheet		Wafer Bump Material				
	Assembly Materials			Part number change		_		afer Bump Process		
Щ	Mechanical Specification		Щ	Test Site		╣		r Fab Site		
Ш	Packing/Shipping/Labeling			Test Process		4		er Fab Materials		
			NI.	Wafer Fab Process				Process		
Description of Change:  Texas Instruments Incorporated is announcing an information only notification.										
The product datasheet(s) is being updated as summarized below.										
The following change history provides further details.										
TEXAS INSTRUMENTS  LM3263  SNVS837B – JUNE 2013 – REVISED APRIL 2016										
Cha	anges from Revision A (A	August 2013) to	Revi	sion B					Page	
<ul> <li>Added Device Information and Pin Configuration and Functions sections, ESD Ratings and Feature Description, Device Functional Modes, Application and Implementation, Power Supply Recommendations, Layout, Device and Documentation Support, and Mechanical, Packaging, and Orderable Information sections</li></ul>										
The	datasheet number	will be chan	gind	1.						
Device Family				Change From:				Chan	ge To:	
LM3263				SNVS837A				SNV	S837B	
These changes may be reviewed at the datasheet links provided. <a href="http://www.ti.com/product/LM3263">http://www.ti.com/product/LM3263</a>										
Reason for Change:										
To more accurately reflect device characteristics.										
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):  No anticipated impact. This is a specification change announcement only. There are no changes										
to the actual device.										
Changes to product identification resulting from this PCN:										
	None.									
	duct Affected:	1								
LM	LM3263TME/NOPB LM3263TMX/NOPB									

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com